

Features

Broadest range of surface mount devices available in the industry

Faster time to trip than standard surface mount devices

RoHS Compliant & Halogen Free

Electrical Characteristics

Part Number	I_H	I_T	T_{Trip}	I_{MAX}	V_{MAX}	$P_{D Typ}$	R_{MIN}	$R1_{MAX}$
	A	A	sec/A	A	V	W	Ω	Ω
K2920L200/24PR	2.0	4.0	8.0/5.0	100	24	1.5	0.035	0.120

I_H =Hold current-maximum current at which the device will not trip at 23°C still air.

I_T =Trip current-minimum current at which the device will always trip at 23°C still air.

T_{trip} =Maximum time to trip(s) at assigned current.

I_{MAX} = Maximum fault current device can withstand without damage at rated voltage (V_{MAX}).

V_{MAX} =Maximum voltage device can withstand without damage at its rated current.

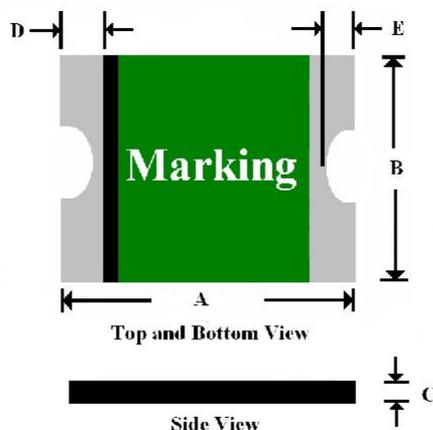
$P_{D Typ}$ =Typical power dissipated from device when in tripped state in 23°C still air environment.

R_{MIN} =Minimum device resistance at 23°C.

$R1_{MAX}$ =Maximum device resistance at 23°C, 1 hour after tripping.

Product Dimensions (Millimeter)

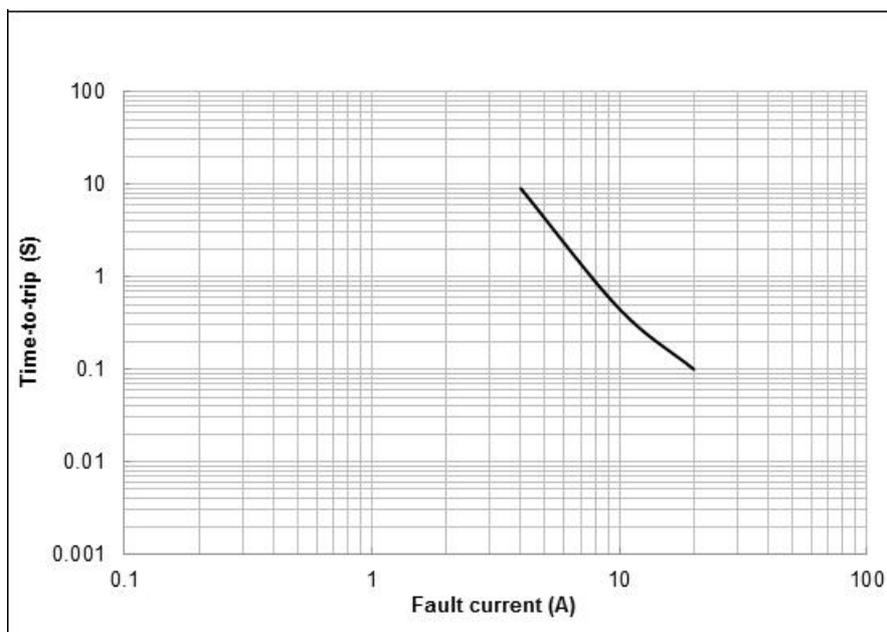
Part Number	A		B		C		D		E	
	Min	Max								
K2920L200/24PR	6.73	7.98	4.80	5.44	0.20	0.80	0.50	1.20	0.50	0.90



Thermal Derating Chart-I_H (A)

Part Number	Maximum ambient operating Temperature(°C)									
	-40	-20	0	23	30	40	50	60	70	85
K2920L200/24PR	2.90	2.68	2.34	2.00	1.84	1.66	1.50	1.32	1.16	0.90

Typical Time-To-Trip at 23°C

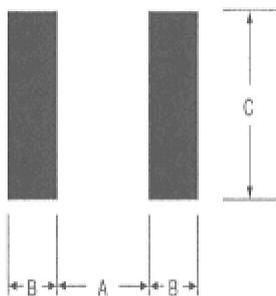


Package Information

Tape & Reel: 2000pcs per reel

Pad Layouts

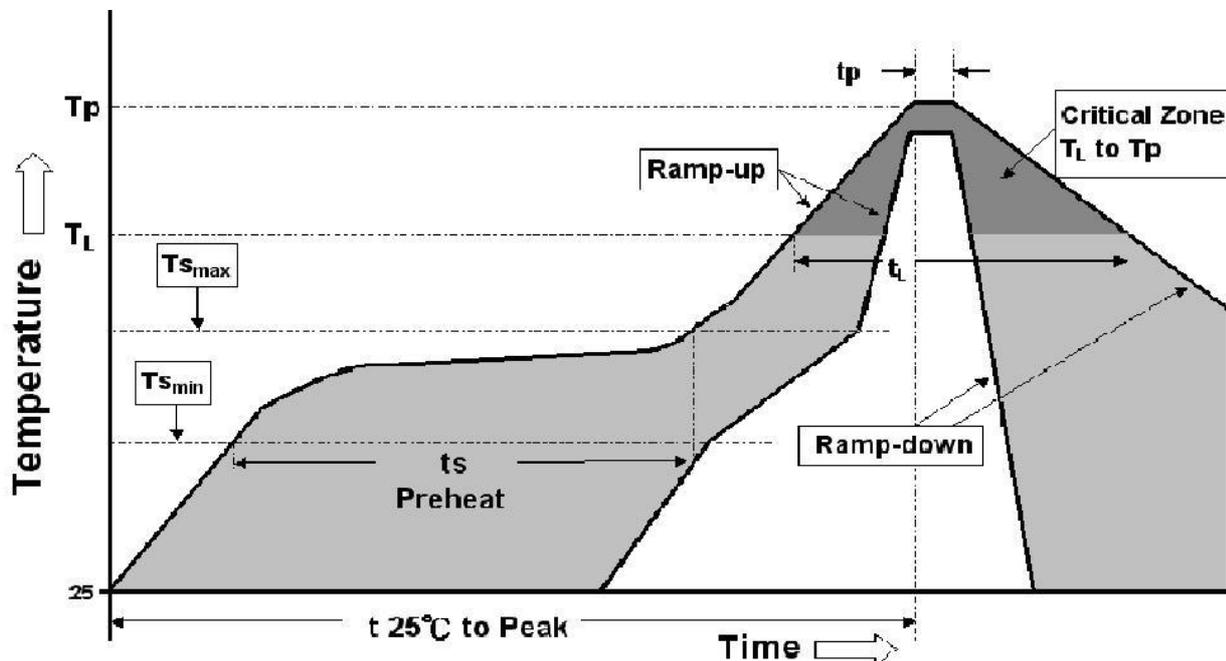
The dimension in the table below provide the recommended pad layout for each device



Pad dimensions (millimeters)

Device	A Nominal	B Nominal	C Nominal
K2920L200/24PR	5.10	2.30	5.60

Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3 °C/second max.
Preheat :	
-Temperature Min (T _{smin})	150 °C
-Temperature Max (T _{smax})	200 °C
-Time (t _{smin} to t _{smax})	60-180 seconds
Time maintained above:	
-Temperature(T _L)	217 °C
-Time (t _L)	60-150 seconds
Peak/Classification Temperature(T _p)	260 °C
Time within 5°C of actual Peak :	
Temperature (t _p)	20-40 seconds
Ramp-Down Rate :	6 °C/second max.
Time 25 °C to Peak Temperature :	8 minutes max.

- Recommended solder paste thickness > 0.25mm.
- Devices cleansing applies standard methods and aqueous solution.
- Use standard industry practices for rework.
- Storage condition : < 30°C / 60%RH

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Note 3: Devices are not designed to be wave soldered to the bottom side of the board.